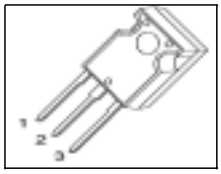
Cool MOS™ Power Transistor

V_{DS}	800	V
$R_{DS(on)}$	0.45	Ω
I_D	11	A

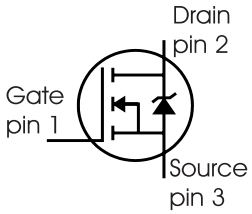
Feature

- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme d*v*/d*t* rated
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC[0)] for target applications

PG-TO247



Type	Package	Ordering Code	Marking
SPW11N80C3	PG-TO247	Q67040-S4440	11N80C3



Maximum Ratings

Parameter	Symbol	Value	Unit
Continuous drain current T_C = 25 °C T_C = 100 °C	I_D	 11 7.1	A
Pulsed drain current, t_p limited by T_{jmax}	$I_{D\ puls}$	33	
Avalanche energy, single pulse I_D = 2.2 A, V_{DD} = 50 V	E_{AS}	470	mJ
Avalanche energy, repetitive t_{AR} limited by T_{jmax}[1] I_D = 11 A, V_{DD} = 50 V	E_{AR}	0.2	
Avalanche current, repetitive t_{AR} limited by T_{jmax}	I_{AR}	11	A
Reverse diode d*v*/d*t* I_S=11A, V_{DS}=480V, T_j=125°C	d*v*/d*t*	6	V/ns
Gate source voltage	V_{GS}	±20	V
Gate source voltage AC (f >1Hz)	V_{GS}	±30	
Power dissipation, T_C = 25°C	P_{tot}	156	W
Operating and storage temperature	T_j, T_{stg}	-55... +150	°C

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain Source voltage slope V_{DS} = 640 V, I_D = 11 A, T_j = 125 °C	dv/dt	50	V/ns

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Thermal resistance, junction - case	R_{thJC}	-	-	0.8	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	62	
Soldering temperature, wavesoldering 1.6 mm (0.063 in.) from case for 10s	T_{sold}	-	-	260	°C

Electrical Characteristics, at Tj=25°C unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=0.25mA	800	-	-	V
Drain-Source avalanche breakdown voltage	$V_{(BR)DS}$	V_{GS}=0V, I_D=11A	-	870	-	
Gate threshold voltage	$V_{GS(th)}$	I_D=680µA, V_{GS}=V_{DS}	2.1	3	3.9	
Zero gate voltage drain current	I_{DSS}	V_{DS}=800V, V_{GS}=0V, T_j=25°C, T_j=150°C	 - -	 0.5 -	 20 200	µA
Gate-source leakage current	I_{GSS}	V_{GS}=20V, V_{DS}=0V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=7.1A, T_j=25°C T_j=150°C	 - -	 0.39 1.1	 0.45 -	Ω
Gate input resistance	R_G	f=1MHz, open Drain	-	0.7	-	

Electrical Characteristics , at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Transconductance	g_{fs}	$V_{DS}\geq 2*I_D*R_{DS(on)max}$, I_D=7.1A	-	7.5	-	S
Input capacitance	C_{iss}	V_{GS}=0V, V_{DS}=25V, f=1MHz	-	1600	-	pF
Output capacitance	C_{oss}		-	800	-	
Reverse transfer capacitance	C_{rss}		-	40	-	
Effective output capacitance,[2] energy related	$C_{o(er)}$	V_{GS}=0V, V_{DS}=0V to 480V	-	44.3	-	pF
Effective output capacitance,[3] time related	$C_{o(tr)}$		-	33.9	-	
Turn-on delay time	$t_{d(on)}$	V_{DD}=400V, V_{GS}=0/10V, I_D=11A, R_G=7.5Ω	-	25	-	ns
Rise time	t_r		-	15	-	
Turn-off delay time	$t_{d(off)}$		-	72	82	
Fall time	t_f		-	7	10	

Gate Charge Characteristics

Gate to source charge	Q_{gs}	V_{DD}=640V, I_D=11A	-	6.5	-	nC
Gate to drain charge	Q_{gd}		-	30	-	
Gate charge total	Q_g	V_{DD}=640V, I_D=11A, V_{GS}=0 to 10V	-	58	75	
Gate plateau voltage	$V_{(plateau)}$	V_{DD}=640V, I_D=11A	-	6	-	V

[0] J-STD20 and JESD22

[1] Repetitve avalanche causes additional power losses that can be calculated as $P_{AV}=E_{AR}*f$.

[2] $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.

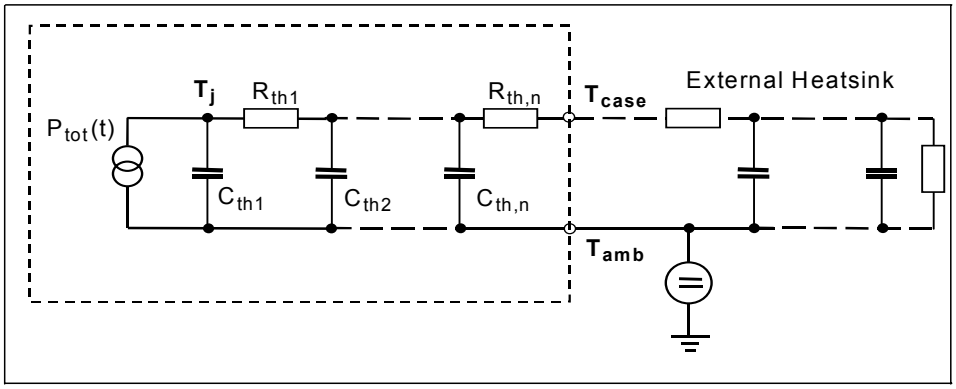
[3] $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.

Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Inverse diode continuous forward current	I_S	T_C=25°C	-	-	11	A
Inverse diode direct current, pulsed	I_{SM}		-	-	33	
Inverse diode forward voltage	V_{SD}	V_{GS}=0V, I_F=I_S	-	1	1.2	V
Reverse recovery time	t_{rr}	V_R=640V, I_F=I_S ,	-	550	-	ns
Reverse recovery charge	Q_{rr}	di_F/dt=100A/µs	-	10	-	µC
Peak reverse recovery current	I_{rrm}		-	33	-	A
Peak rate of fall of reverse recovery current	di_{rr}/dt		-	1000	-	A/µs

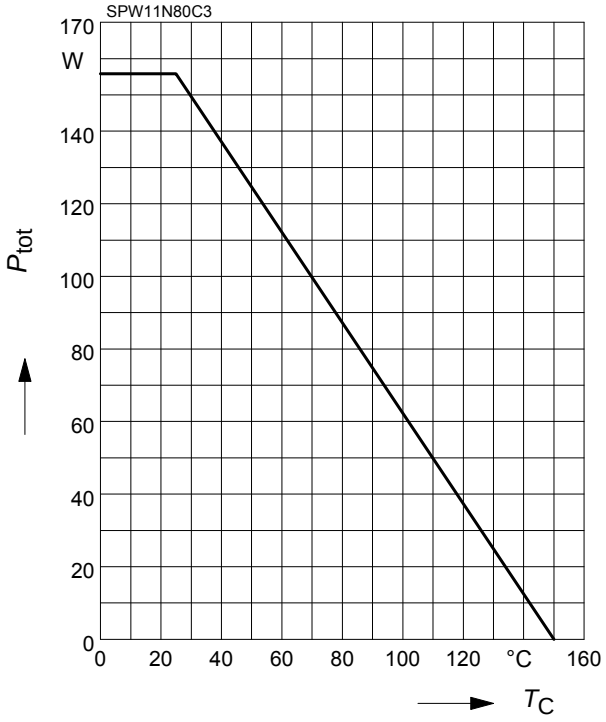
Typical Transient Thermal Characteristics

Symbol	Value	Unit	Symbol	Value	Unit
	typ.			typ.	
Thermal resistance			Thermal capacitance		
R_{th1}	0.012	K/W	C_{th1}	0.0002493	Ws/K
R_{th2}	0.023		C_{th2}	0.0009399	
R_{th3}	0.043		C_{th3}	0.001298	
R_{th4}	0.138		C_{th4}	0.003617	
R_{th5}	0.158		C_{th5}	0.01	
R_{th6}	0.064		C_{th6}	0.083	



1 Power dissipation

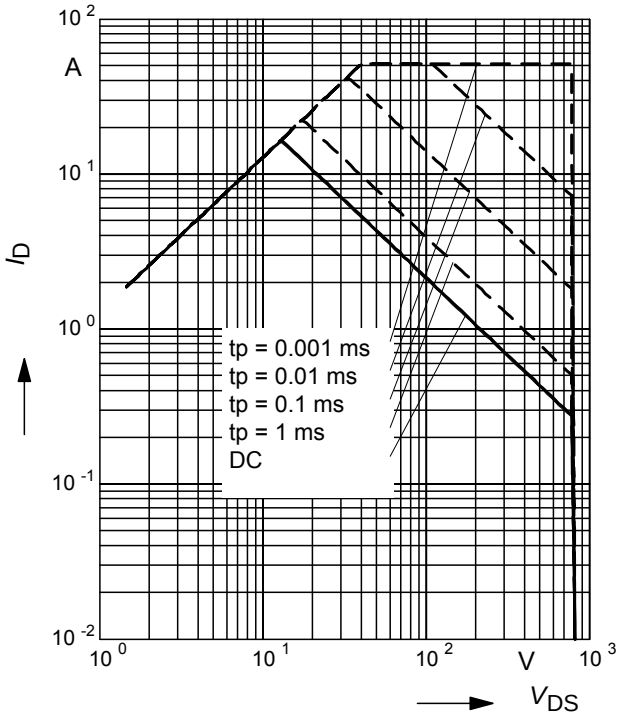
$P_{tot} = f(T_C)$



2 Safe operating area

$I_D = f(V_{DS})$

parameter : $D = 0$, T_C=25°C



3 Safe operating area FullPAK

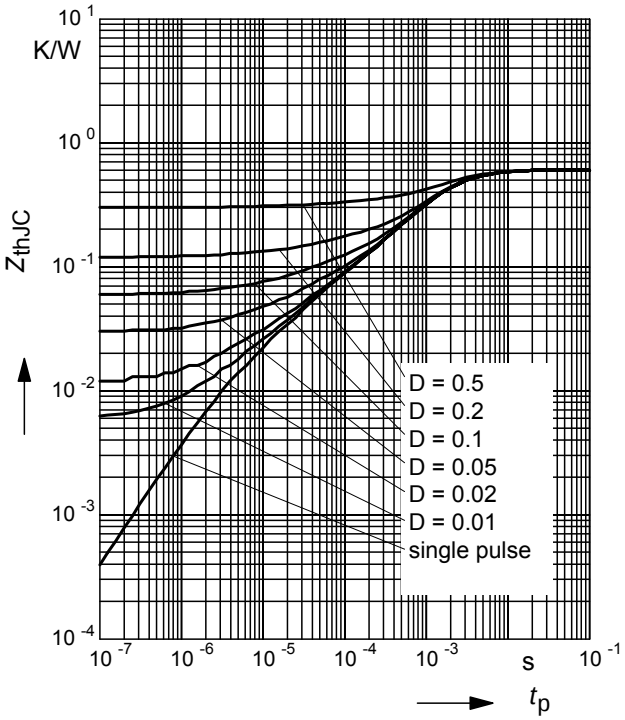
$I_D = f(V_{DS})$

parameter: $D = 0$, $T_C = 25°C$

4 Transient thermal impedance

$Z_{thJC} = f(t_p)$

parameter: $D = t_p/T$



5 Transient thermal impedance FullPAK

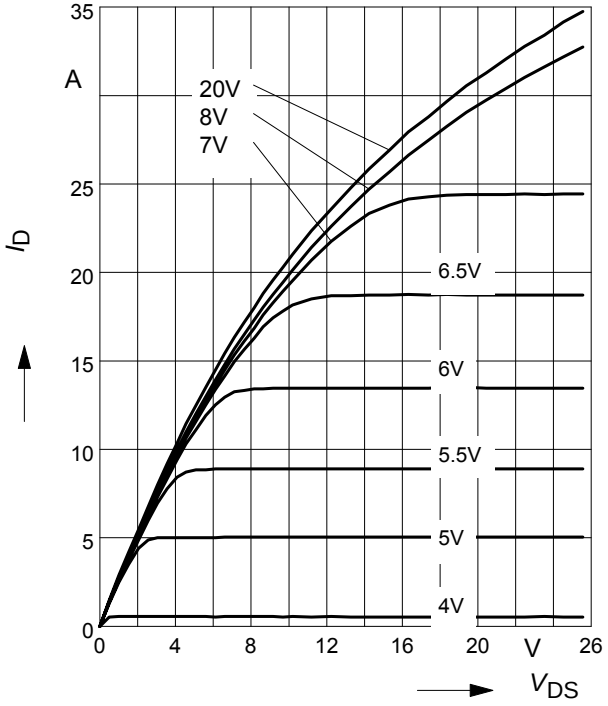
$Z_{thJC} = f(t_p)$

parameter: $D = t_p/t$

6 Typ. output characteristic

$I_D = f(V_{DS})$; T_j=25°C

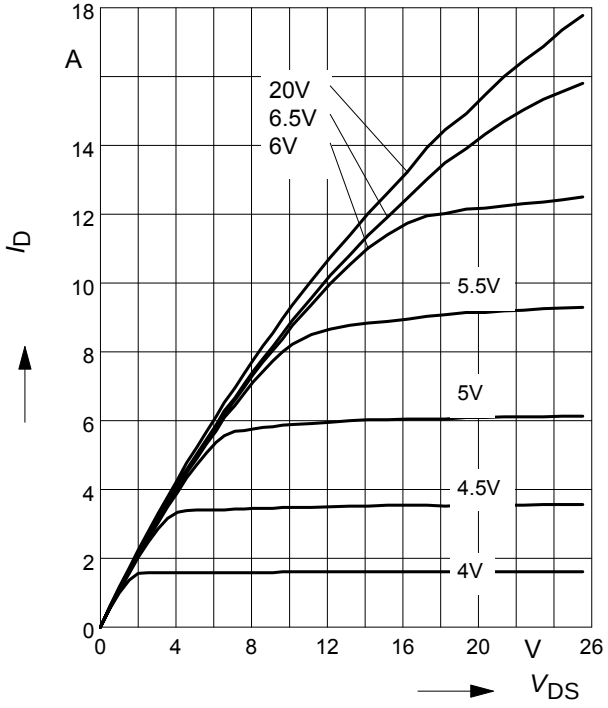
parameter: t_p = 10 µs, V_{GS}



7 Typ. output characteristic

$I_D = f(V_{DS})$; T_j=150°C

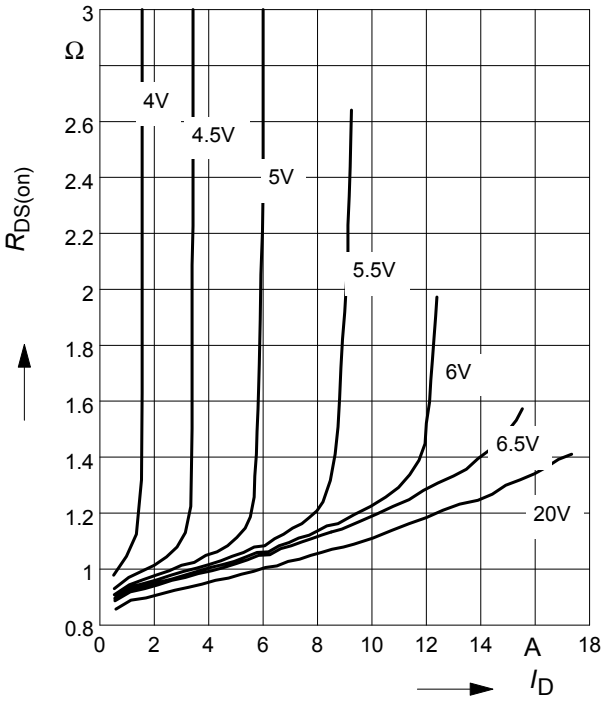
parameter: t_p = 10 µs, V_{GS}



8 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D)$

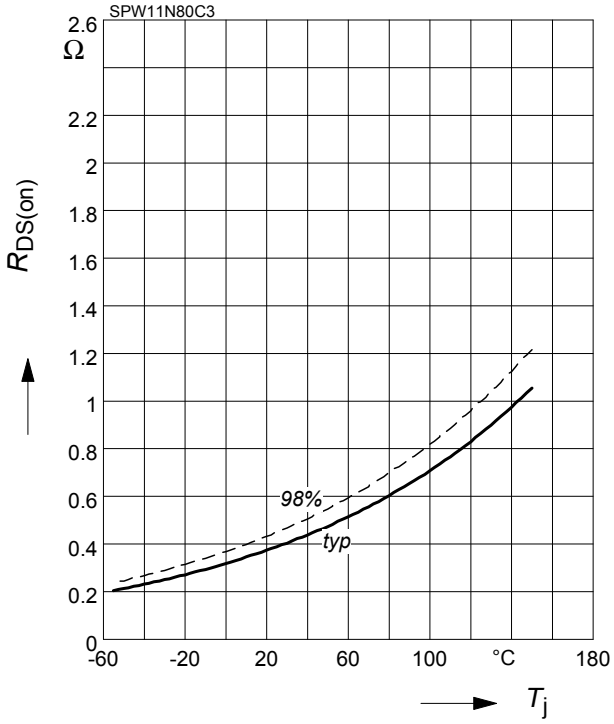
parameter: T_j=150°C, V_{GS}



9 Drain-source on-state resistance

$R_{DS(on)} = f(T_j)$

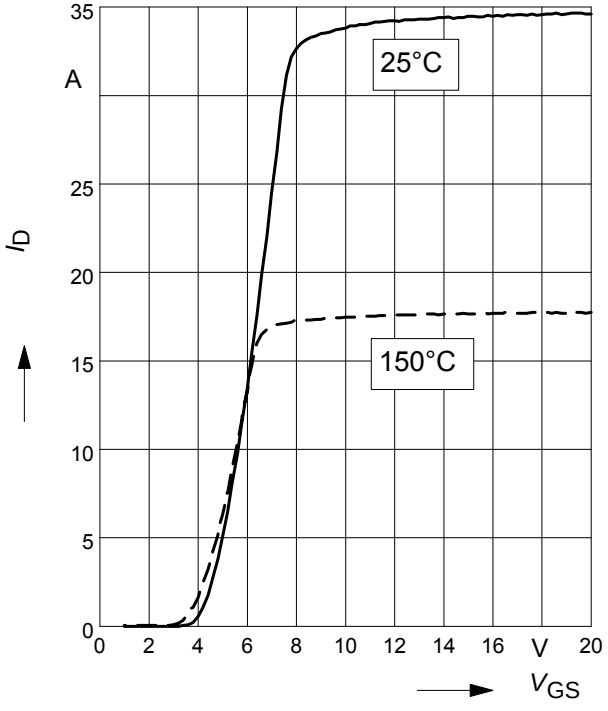
parameter : I_D = 7.1 A, V_{GS} = 10 V



10 Typ. transfer characteristics

$I_D = f(V_{GS})$; $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

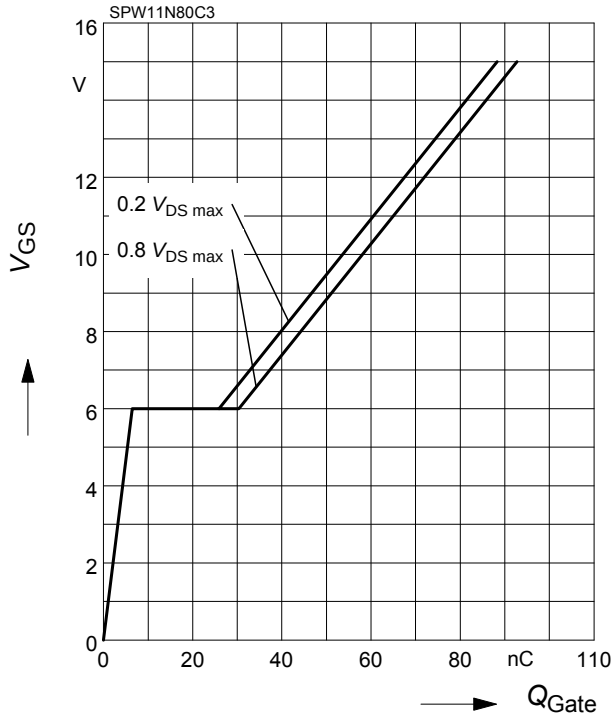
parameter: t_p = 10 µs



11 Typ. gate charge

$V_{GS} = f(Q_{Gate})$

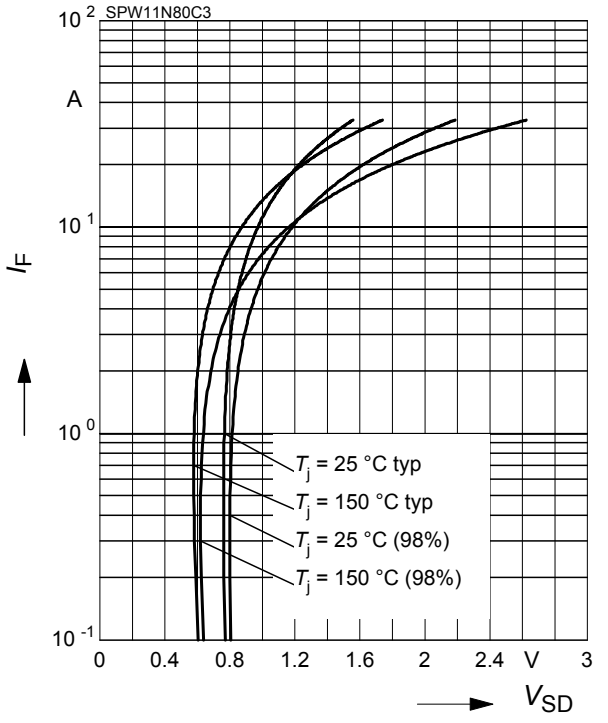
parameter: I_D = 11 A pulsed



12 Forward characteristics of body diode

$I_F = f(V_{SD})$

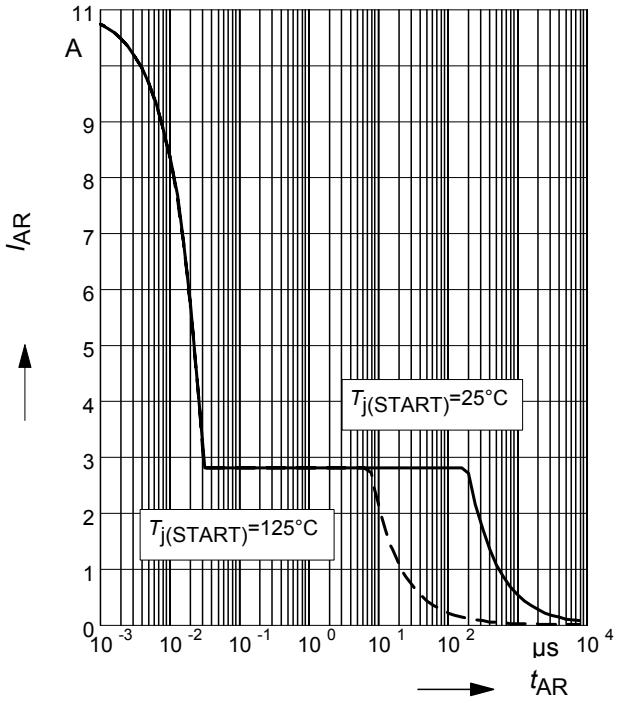
parameter: T_j , tp = 10 µs



13 Avalanche SOA

$I_{AR} = f(t_{AR})$

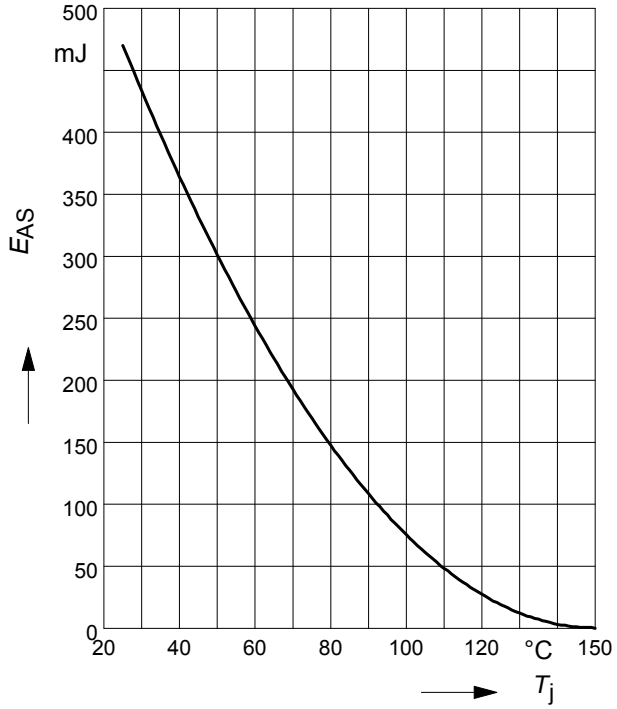
par.: $T_j \leq 150$ °C



14 Avalanche energy

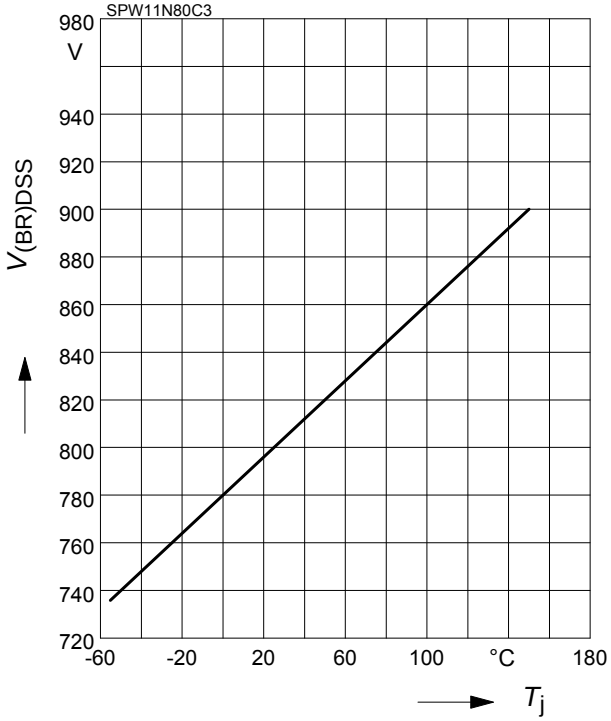
$E_{AS} = f(T_j)$

par.: I_D = 2.2 A, V_{DD} = 50 V



15 Drain-source breakdown voltage

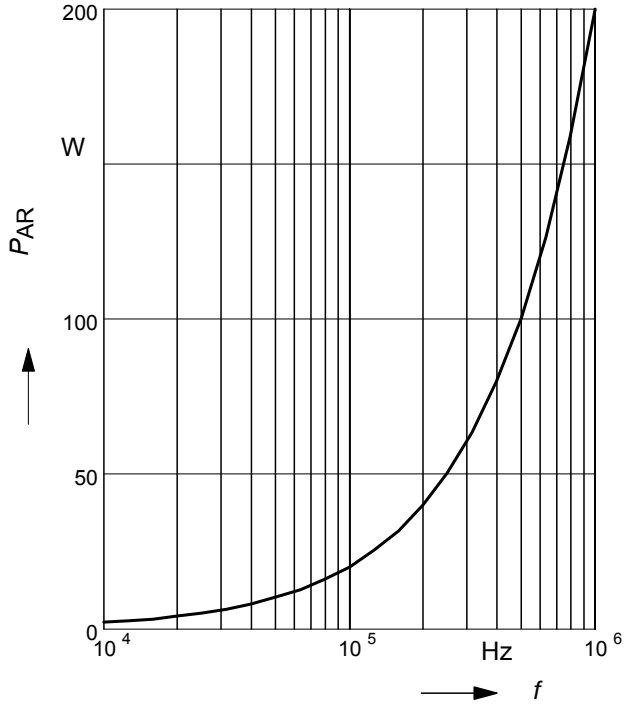
$V_{(BR)DSS} = f(T_j)$



16 Avalanche power losses

$P_{AR} = f(f)$

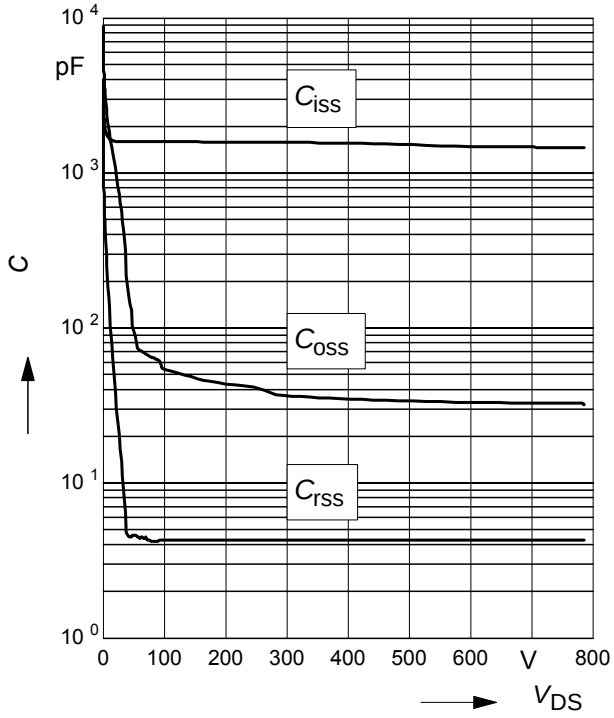
parameter: E_{AR}=0.2mJ



17 Typ. capacitances

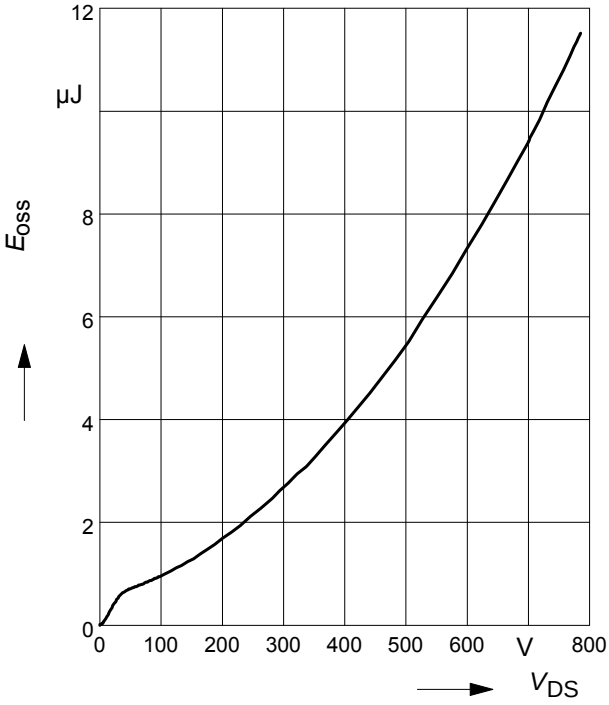
$C = f(V_{DS})$

parameter: V_{GS}=0V, f=1 MHz

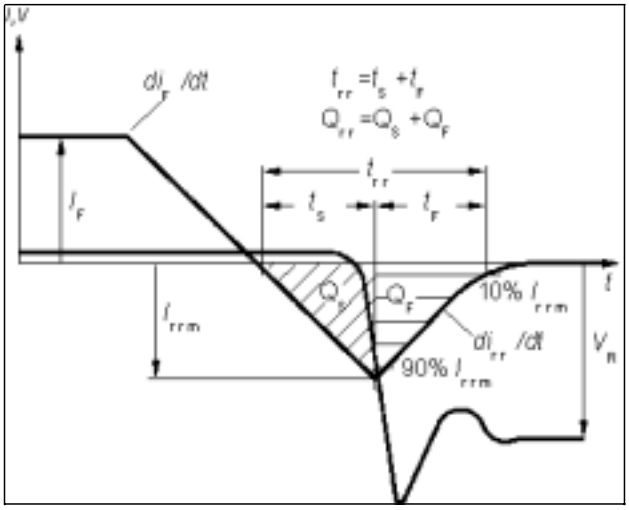


18 Typ. C_{oss} stored energy

$E_{oss}=f(V_{DS})$



Definition of diodes switching characteristics



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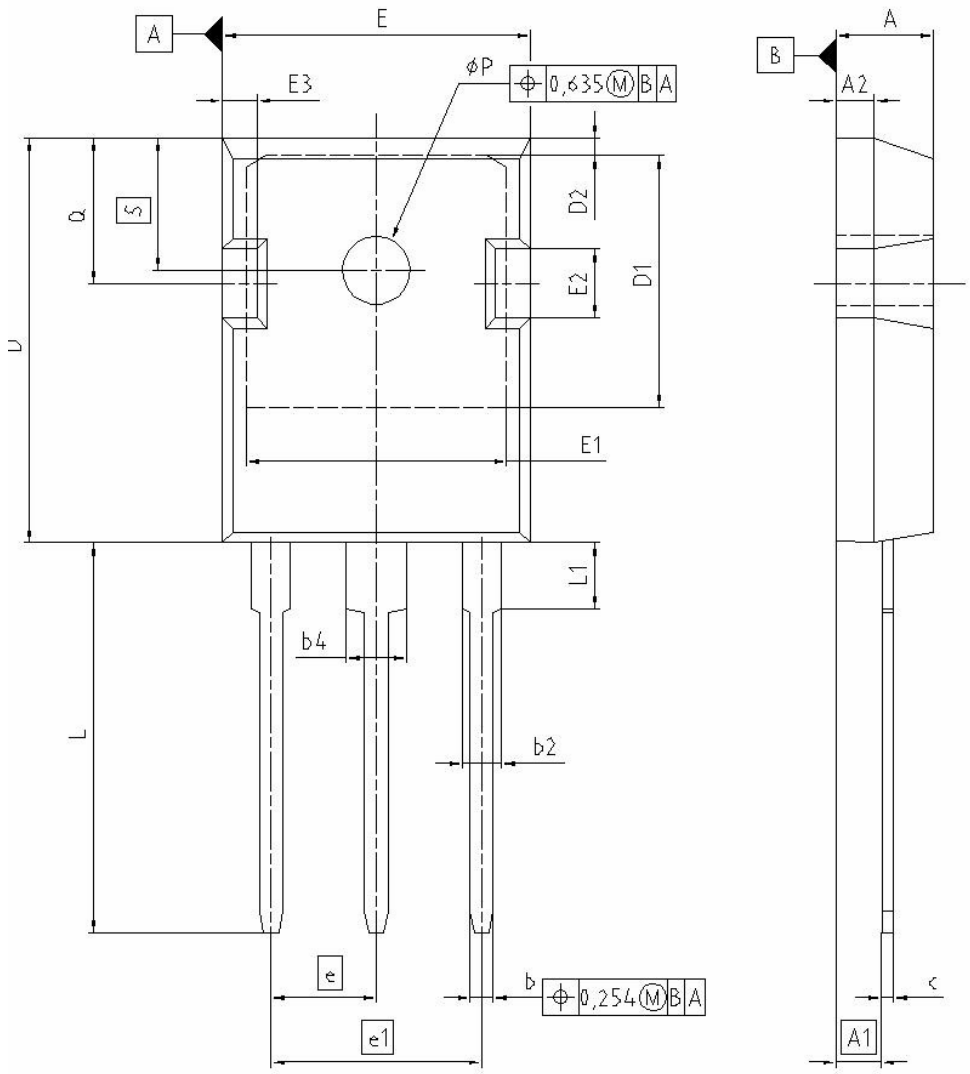

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.903	5.157	0.193	0.203
A1	2.273	2.527	0.092	0.096
A2	1.853	2.107	0.075	0.081
b	1.073	1.327	0.047	0.052
b2	1.903	2.386	0.075	0.094
b4	2.870	3.454	0.113	0.136
c	0.549	0.752	0.024	0.030
D	20.823	21.077	0.820	0.830
D1	17.323	17.831	0.682	0.702
D2	1.063	1.317	0.042	0.052
E	15.773	16.027	0.621	0.631
E1	13.893	14.147	0.547	0.557
E2	3.683	3.937	0.145	0.155
E3	1.683	1.937	0.066	0.076
e	5.450		0.215	
e1	10.900		0.430	
N	3		3	
L	20.053	20.307	0.789	0.799
L1	4.168	4.472	0.164	0.176
øP	3.559	3.661	0.140	0.144
Q	5.493	5.747	0.216	0.226
S	6.043	6.297	0.238	0.248

REFERENCE	JEDEC TO247-AD
SCALE	0 5 5 7.5mm
EUROPEAN PROJECTION	
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